**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF THE CLAIMS:**

1-8 (Canceled).

9. (Currently Amended) A press-fit diode, comprising:

a diode chip;

a base contact for pressing the press-fit diode into a substrate, wherein the base contact is attached to the diode chip and forms a first terminal of the press-fit diode; and

a wire contact which forms a second terminal of the press-fit diode, wherein the wire contact is attached to the diode chip and is at least partially provide with a silver layer, wherein the silver layer is directly applied on a nickel layer.

10. (Previously Presented) The press-fit diode as recited in claim 9, wherein a section of the wire contact attached to the diode chip is not provided with the silver layer.

11. (Previously Presented) The press-fit diode as recited in claim 10, wherein the base contact is not provided with a silver layer.

12. (Canceled).

13. (Currently Amended) A method for manufacturing a press-fit diode, comprising:

providing a diode chip;

providing a base contact configured for pressing the press-fit diode into a substrate, wherein the base contact forms a first terminal of the press-fit diode;

providing a wire contact which forms a second terminal of the press-fit diode, wherein the wire contact is at least partially provided with a silver layer, which is directly applied on a nickel layer; and

fixedly connecting the wire contact, the base contact, and the diode chip to one another.

14. (Previously Presented) The method as recited in claim 13, wherein a section of the wire contact attached to the diode chip is not provided with the silver layer.

15. (Previously Presented) The method as recited in claim 13, wherein the base contact is not provided with a silver layer.

16. (Previously Presented) The method as recited in claim 14, wherein the base contact is not provided with a silver layer.

17. (Currently Amended) The method as recited in claim 13, wherein the wire contact is made of copper, and wherein the wire contact ~~is further provided with a~~ has the nickel layer on which the silver layer is applied.

18. (Currently Amended) The method as recited in claim 14, wherein the wire contact is made of copper, and wherein the wire contact ~~is further provided with a~~ has the nickel layer on which the silver layer is applied.

19. (New) The press-fit diode as recited in claim 9, wherein the silver layer is applied before the press-fit diode is assembled.

20. (New) The press-fit diode as recited in claim 9, wherein a region for attaching the diode chip is recessed.

21. (New) The press-fit diode as recited in claim 9, wherein the wire contact is inserted in a rack with a wire shaft pointing downward, and wherein the wire shaft is immersed in an electroplating vat.

22. (New) The press-fit diode as recited in claim 9, wherein a central section of the press-fit diode is sheathed in plastic to protect the diode chip.

23. (New) The press-fit diode as recited in claim 9, wherein the press-fit diode is electroplated in bulk in a drum process.

24. (New) The method as recited in claim 13, further comprising:

applying the silver layer before the press-fit diode is assembled.

25. (New) The method as recited in claim 13, wherein a region for attaching the diode chip is recessed.

26. (New) The method as recited in claim 13, further comprising:

inserting the wire contact in a rack with a wire shaft pointing downward; and

immersing the wire shaft in an electroplating vat.

27. (New) The method as recited in claim 13, further comprising:

sheathing a central section of the press-fit diode to protect the diode chip.

28. (New) The method as recited in claim 13, wherein the press-fit diode is electroplated in bulk in a drum process.

29. (New) The press-fit diode as recited in claim 9, wherein the silver layer is applied before the press-fit diode is assembled, wherein a region for attaching the diode chip is recessed, wherein the wire contact is inserted in a rack with a wire shaft pointing downward, wherein the wire shaft is immersed in an electroplating vat, wherein a central section of the press-fit diode is sheathed in plastic to protect the diode chip, and wherein the press-fit diode is electroplated in bulk in a drum process

30. (New) The method as recited in claim 13, further comprising:

inserting the wire contact in a rack with a wire shaft pointing downward;

immersing the wire shaft in an electroplating vat. wherein a region for attaching the diode chip is recessed; and

sheathing a central section of the press-fit diode to protect the diode chip;

wherein the press-fit diode is electroplated in bulk in a drum process.